

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	793201	((stack stacked stacking stackable) (first second) (top bottom) (upper lower)) with (dice die chip ic semiconductor (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:07
L2	404097	(pad terminal electrode) same wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:08
L3	27259	1 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:09
L4	5669	((insulator insulative insulation) (adhesion adhesive)) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:12
L5	3384	(package packaging packaged) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:12
L6	3054	((insulator insulative insulation) and (adhesion adhesive)) and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:12
L7	2339	(package packaging packaged) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:12
L8	2184	(substrate carrier board pcb ((printed wiring) adj3 board)) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/09 11:13